

## Description

The DGD2110 and DGD2113 are high-voltage/high-speed MOSFET and IGBT drivers with independent high-side and low-side outputs. The high-side driver features floating supply for operation at up to 500V/600V. The 10ns (max)/20ns (max) propagation delay matching between the high- and the low-side drivers allows high-frequency operation.

The DGD2110 and DGD2113 logic inputs are compatible with standard CMOS levels (as low as 3.3V) while driver outputs feature high-pulse current buffers designed for minimum driver cross conduction.

The DGD2110 and DGD2113 are offered in a SO-16 (Type TH) package. They operate over an extended -40°C to +125°C temperature range.

## Applications

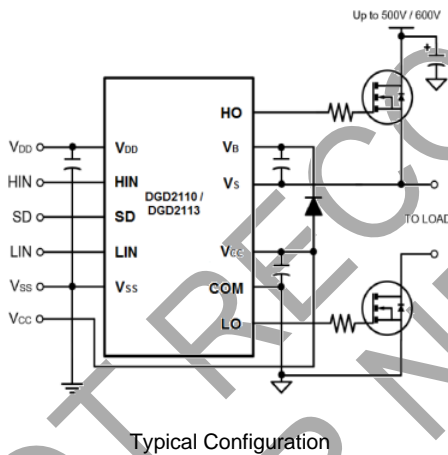
- DC-DC converters
- DC-AC inverters
- AC-DC power supplies
- Motor controls
- Class D Power amplifiers

## Features

- Drives Two N-Channel MOSFETs or IGBTs in High-Side/Low-Side Configuration
- Floating High-Side Operates to 600V
- 2.5A Sink/2.5A Source Typical Output Currents
- Outputs Tolerant to Negative Transients
- Wide Gate Driver Supply Voltage Range: 10V to 20V
- Wide Logic Input Supply Voltage Range: 3.3V to 20V
- Wide Logic Supply Offset Voltage Range: -5V to 5V
- 15ns (typ) Rise/13ns (typ) Fall Time with 1000pF Load
- 105ns (typ) Turn-On/94ns (typ) Turn-Off Delay Time
- Cycle-by-Cycle Edge-Triggered Shutdown Circuitry
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](https://www.diodes.com/contact-us) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

## Mechanical Data

- Package: SO-16
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.130 grams (Approximate)



Typical Configuration



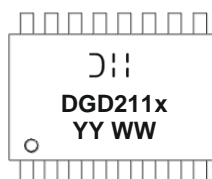
SO-16 (Type TH)  
Top View

## Ordering Information (Note 4)

Part Number	Package	Marking	Reel Size (inches)	Tape Width (mm)	Packing	
					Qty.	Carrier
DGD2110S16-13	SO-16 (Type TH)	DGD2110	13	16	1500	Reel
DGD2113S16-13	SO-16 (Type TH)	DGD2113	13	16	1500	Reel

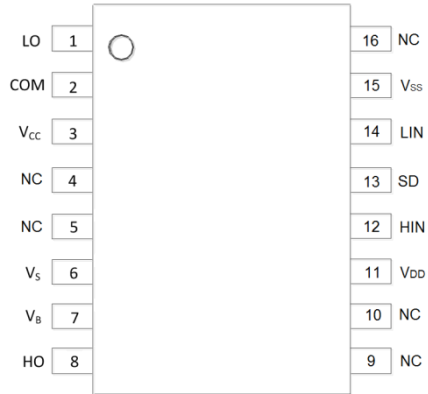
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



D = Manufacturer's Marking  
 DGD211x = Product Type Marking Code (See Table Above)  
 YY = Year (ex: 24 = 2024)  
 WW = Week (01 to 53)

**Pin Diagrams**

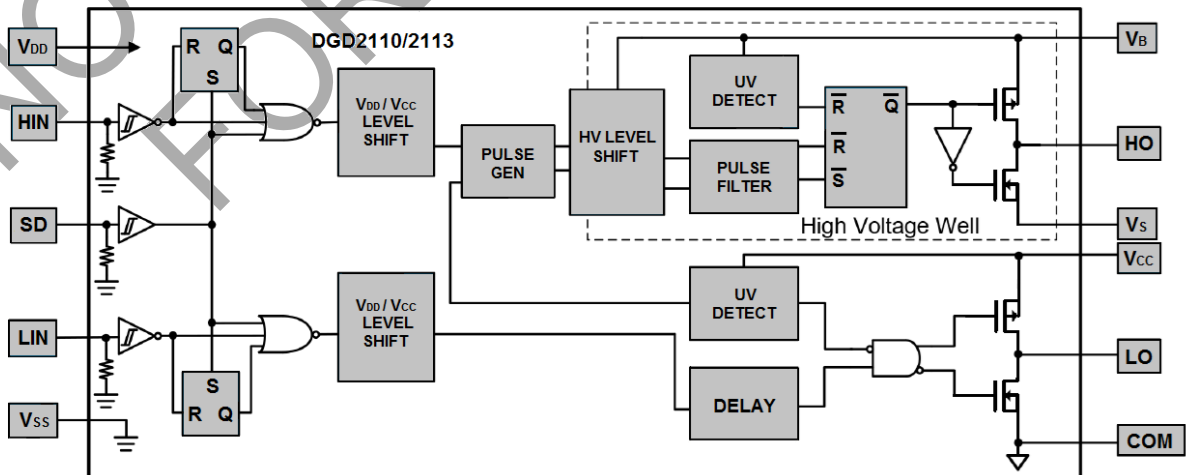


Top View: SO-16 (Type TH)

**Pin Descriptions**

Pin Number	Pin Name	Function
1	LO	Low-side gate driver output pin
2	COM	Low-side gate driver power supply return pin
3	Vcc	Low-side gate driver power supply pin
4, 5, 9, 10, 16	NC	No connect pin (No internal connection)
6	Vs	High-side gate driver floating power supply return pin
7	Vb	High-side gate driver floating power supply pin
8	HO	High-side gate drive output pin
11	VDD	Logic power supply pin
12	HIN	Logic input pin for high-side gate driver output. HIN and HO are in phase
13	SD	Logic input shutdown pin
14	LIN	Logic input pin for low-side gate driver output. LIN and LO are in phase
15	Vss	Logic ground pin

**Functional Block Diagram**



**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage (DGD2110)	V <sub>B</sub>	-0.3 to +524	V
High-Side Floating Supply Voltage (DGD2113)	V <sub>B</sub>	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V <sub>S</sub>	V <sub>B</sub> -24 to V <sub>B</sub> +0.3	V
High-Side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub> -0.3 to V <sub>S</sub> +0.3	V
Offset Supply Voltage Transient	dV <sub>S</sub> / dt	50	V/ns
Low-Side Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +24	V
Low-Side Output Voltage	V <sub>LO</sub>	-0.3 to V <sub>CC</sub> +0.3	V
Logic Supply Voltage	V <sub>DD</sub>	-0.3 to V <sub>SS</sub> +24	V
Logic Supply Offset Voltage	V <sub>SS</sub>	V <sub>CC</sub> -24 to V <sub>CC</sub> +0.3	V
Logic Input Voltage (HIN, LIN, and SD)	V <sub>IN</sub>	V <sub>SS</sub> -0.3 to V <sub>DD</sub> +0.3	V

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P <sub>D</sub>	1.25	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	90	°C/W
Thermal Resistance, Junction to Case (Note 5)	R <sub>θJC</sub>	45	°C/W
Operating Temperature	T <sub>J</sub>	+150	°C
Lead Temperature (Soldering, 10 seconds)	T <sub>L</sub>	+300	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

**Recommended Operating Conditions**

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	V <sub>B</sub>	V <sub>S</sub> + 10	V <sub>S</sub> + 20	V
High-Side Floating Supply Offset Voltage	DGD2110	V <sub>S</sub>	500	V
High-Side Floating Supply Offset Voltage	DGD2113	V <sub>S</sub>	600	V
High-Side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub>	V <sub>B</sub>	V
Low-Side Fixed Supply Voltage	V <sub>CC</sub>	10	20	V
Low-Side Output Voltage	V <sub>LO</sub>	0	V <sub>CC</sub>	V
Logic Supply Voltage	V <sub>DD</sub>	V <sub>SS</sub> + 3	V <sub>SS</sub> + 20	V
Logic Supply Offset Voltage	V <sub>SS</sub>	-5 (Note 7)	5	V
Logic Input Voltage (HIN, LIN, and SD)	V <sub>IN</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

Notes: 6. Logic operation for V<sub>S</sub> = -4V to +500V.

7. When V<sub>DD</sub> < 5V, the minimum V<sub>SS</sub> offset is limited to -V<sub>DD</sub>.

**DC Electrical Characteristics** ( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ,  $V_{DD}$ ) = 15V,  $V_{SS}$  = COM, @ $T_A$  = +25°C unless otherwise specified.) (Note 8)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage (Note 9)	$V_{IH}$	9.5	—	—	V	—
Logic "0" Input Voltage (Note 9)	$V_{IL}$	—	—	6.0	V	—
High-Level Output Voltage, $V_{BIAS} - V_O$	$V_{OH}$	—	—	1.4	V	$I_O = 0mA$
Low-Level Output Voltage, $V_O$	$V_{OL}$	—	—	0.15	V	$I_O = 20mA$
Offset Supply Leakage Current	$I_{LK}$	—	—	50	$\mu A$	$V_B = V_S = 500V/600V$
Quiescent $V_{BS}$ Supply Current	$I_{BSQ}$	—	55	230	$\mu A$	$V_{IN} = 0V$ or $V_{DD}$
Quiescent $V_{CC}$ Supply Current	$I_{CCQ}$	—	56	340	$\mu A$	$V_{IN} = 0V$ or $V_{DD}$
Quiescent $V_{DD}$ Supply Current	$I_{DDQ}$	—	0.6	30	$\mu A$	$V_{IN} = 0V$ or $V_{DD}$
Logic "1" Input Bias Current	$I_{IN+}$	—	20	40	$\mu A$	$V_{IN} = V_{DD}$
Logic "0" Input Bias Current	$I_{IN-}$	—	—	5.0	$\mu A$	$V_{IN} = 0V$
$V_{BS}$ Supply Undervoltage Positive Going Threshold	$V_{BSUV+}$	7.5	8.6	9.7	V	—
$V_{BS}$ Supply Undervoltage Negative Going Threshold	$V_{BSUV-}$	7.0	8.2	9.4	V	—
$V_{CC}$ Supply Undervoltage Positive Going Threshold	$V_{CCUV+}$	7.4	8.5	9.6	V	—
$V_{CC}$ Supply Undervoltage Negative Going Threshold	$V_{CCUV-}$	7.0	8.2	9.4	V	—
Output High Short-Circuit Pulsed Current	$I_{O+}$	2.0	2.5	—	A	$V_O = 0V$ , $V_{IN} = V_{DD}$ $P_W \leq 10\mu s$
Output Low Short-Circuit Pulsed Current	$I_{O-}$	2.0	2.5	—	A	$V_O = 15V$ , $V_{IN} = 0V$ $P_W \leq 10\mu s$

- Notes:
- The  $V_{IN}$  and  $I_{IN}$  parameters are referenced to  $V_{SS}$  and are applicable to all three logic input pins: HIN, LIN, and SD. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output pins: HO and LO.
  - For optimal operation, it is recommended that the input pulses (HIN and LIN) should have a minimum amplitude of 9.5V ( $V_{DD} = 15V$ ) with a minimum pulse width of 200ns.

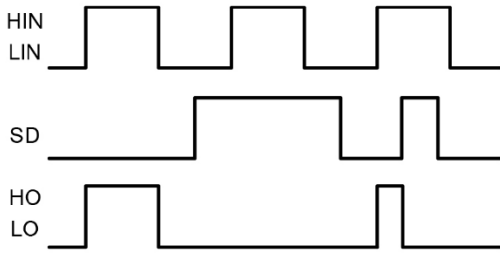
**AC Electrical Characteristics**

( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ,  $V_{DD}$ ) = 15V,  $C_L = 1000pF$ ,  $V_{SS} = COM$ , @ $T_A = +25^\circ C$ , unless otherwise specified.)

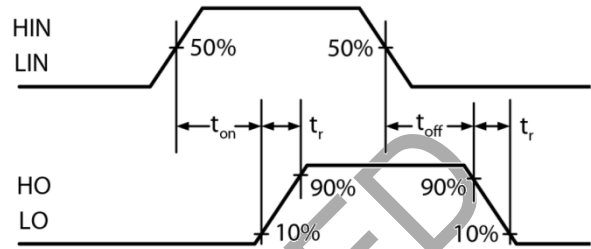
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-On Propagation Delay	$t_{ON}$	—	105	150	ns	$V_S = 0V$
Turn-Off Propagation Delay	$t_{OFF}$	—	94	125	ns	$V_S = 500V/600V$
Shut Down Propagation Delay	$t_{SD}$	—	70	140	ns	$V_S = 500V/600V$
Turn-On Rise Time	$t_r$	—	15	35	ns	—
Turn-Off Fall Time	$t_f$	—	13	25	ns	—
Delay Matching	DGD2110	$t_{DM}$	—	10	—	—
Delay Matching	DGD2113	$t_{DM}$	—	20	—	—

NOT RECOMMENDED FOR NEW DESIGN

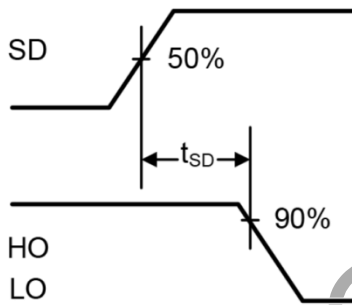
**Timing Waveforms**



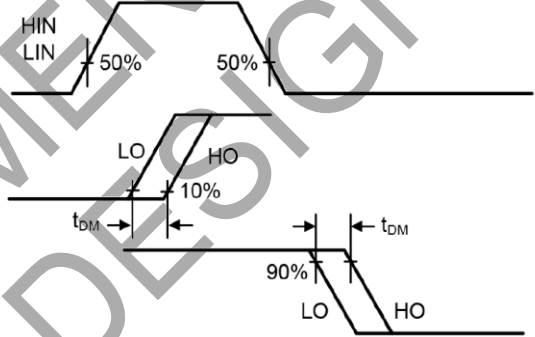
**Figure 1.** Input / Output Timing Diagram



**Figure 2.** Switching Time Waveform Definitions



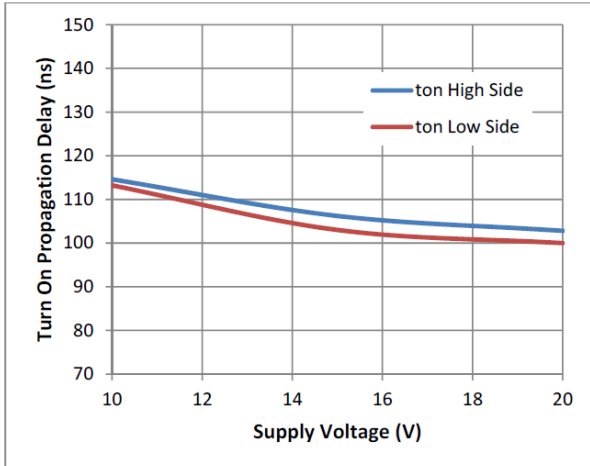
**Figure 3.** Shutdown Waveform Definitions



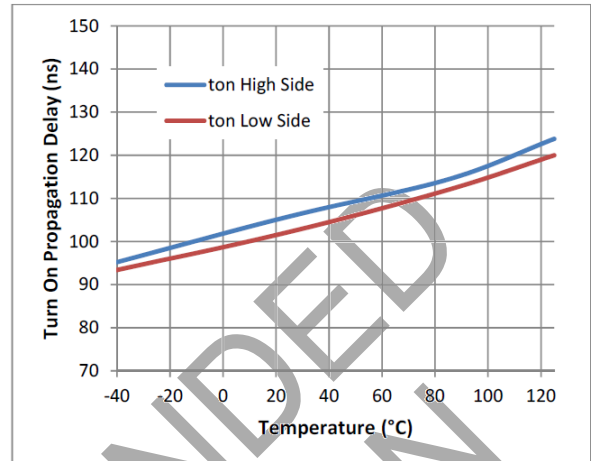
**Figure 4.** Delay Matching Waveform Definitions

NOT RECOMMENDED FOR NEW DESIGN

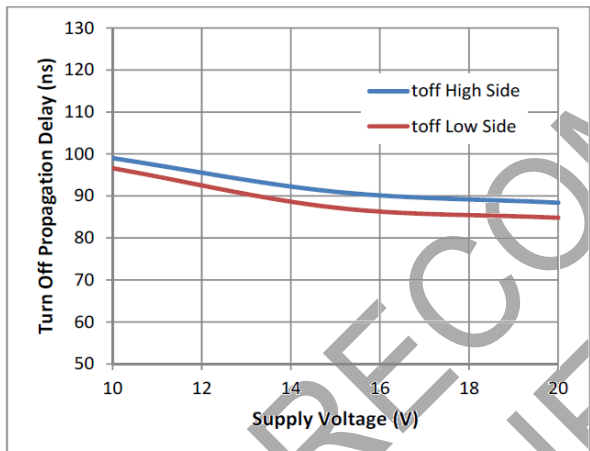
**Typical Performance Characteristics** ( $V_{CC} = 15V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.)



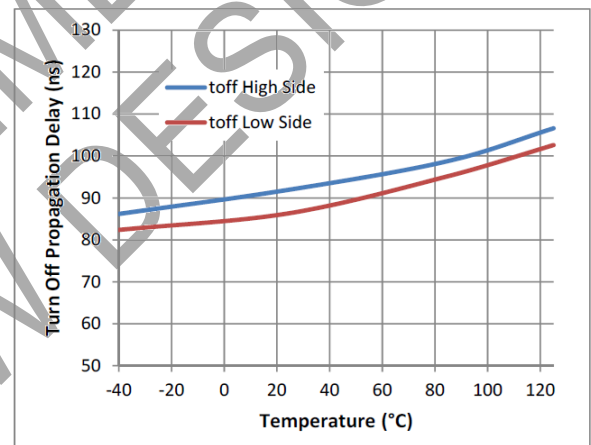
**Figure 5.** Turn-on Propagation Delay vs. Supply Voltage



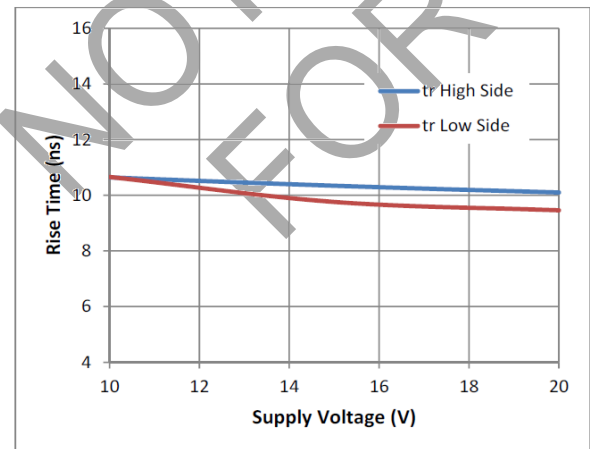
**Figure 6.** Turn-on Propagation Delay vs. Temperature



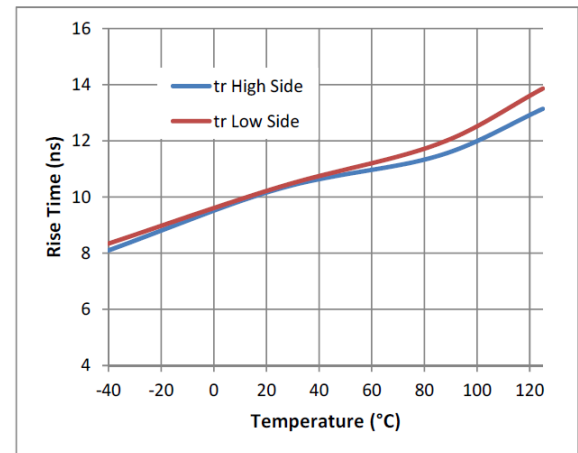
**Figure 7.** Turn-off Propagation Delay vs. Supply Voltage



**Figure 8.** Turn-off Propagation Delay vs. Temperature

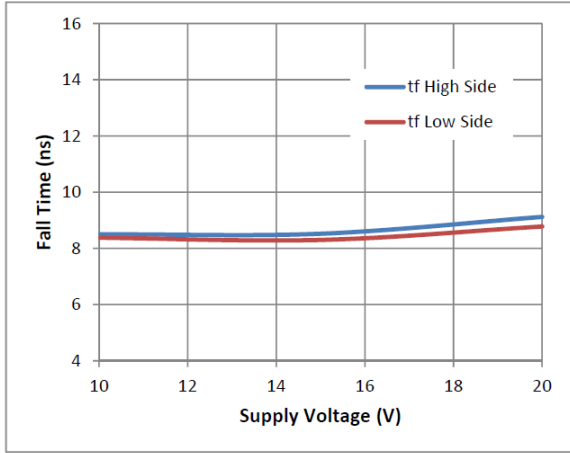


**Figure 9.** Rise Time vs. Supply Voltage

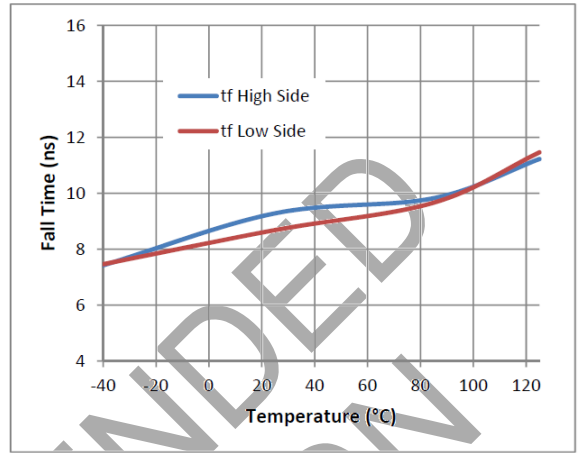


**Figure 10.** Rise Time vs. Temperature

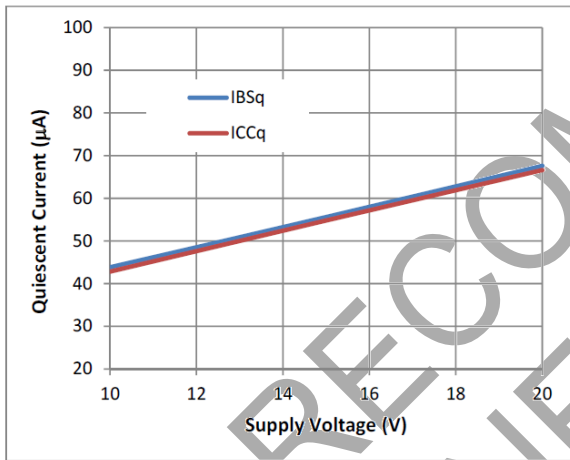
**Typical Performance Characteristics** ( $V_{CC} = 15V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.) (continued)



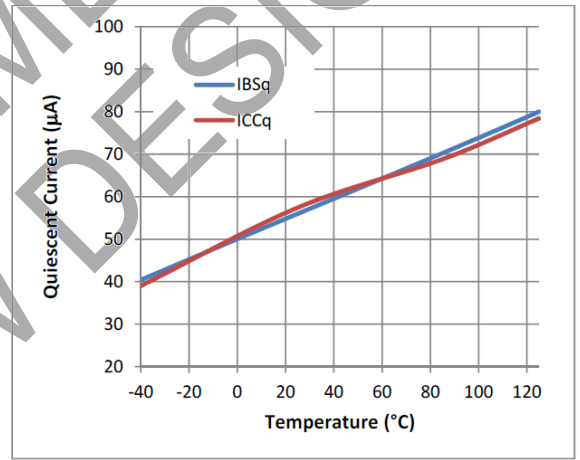
**Figure 11.** Fall Time vs. Supply Voltage



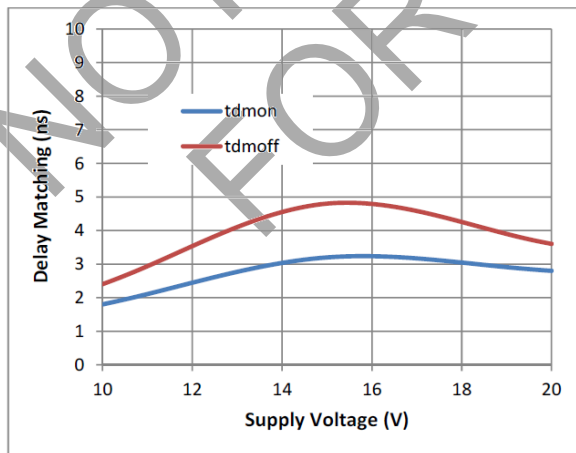
**Figure 12.** Fall Time vs. Temperature



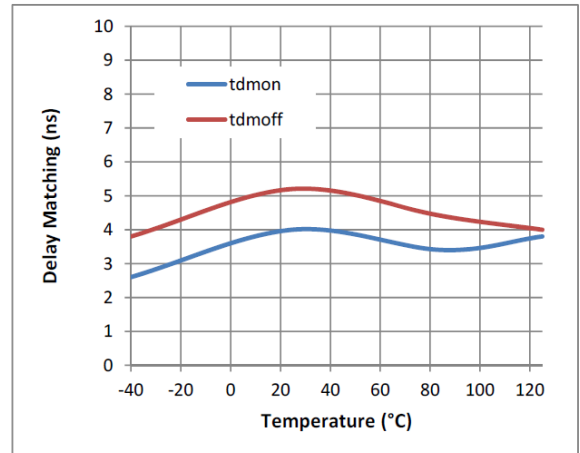
**Figure 13.** Quiescent Current vs. Supply Voltage



**Figure 14.** Quiescent Current vs. Temperature

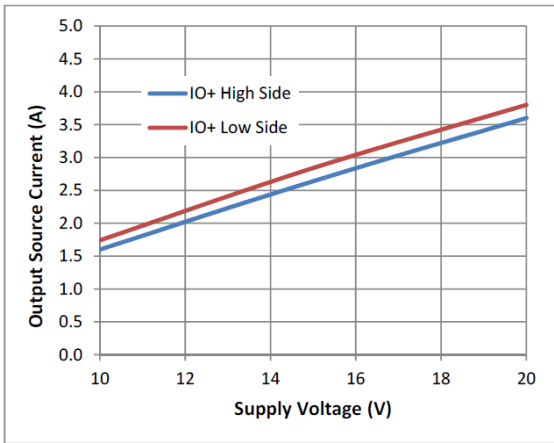


**Figure 15.** Delay Matching vs. Supply Voltage

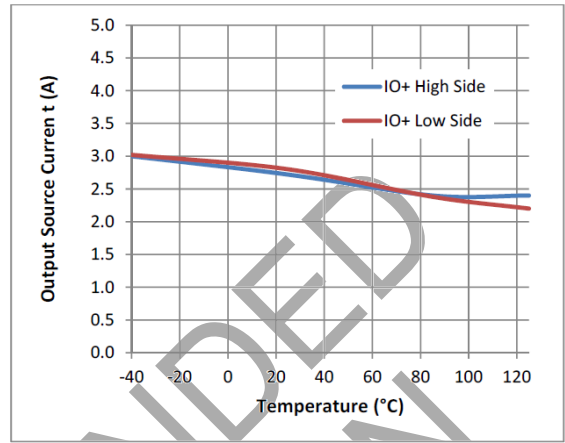


**Figure 16.** Delay Matching vs. Temperature

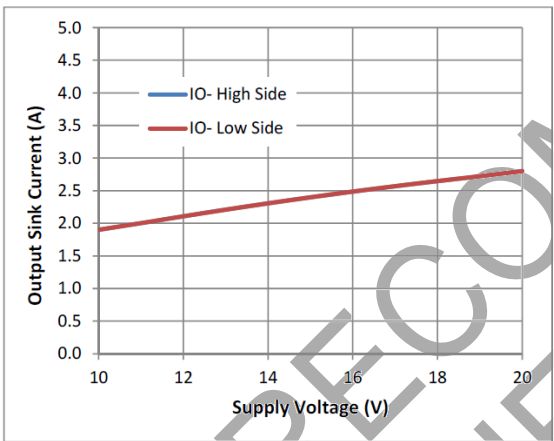
**Typical Performance Characteristics** ( $V_{CC} = 15V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.) (continued)



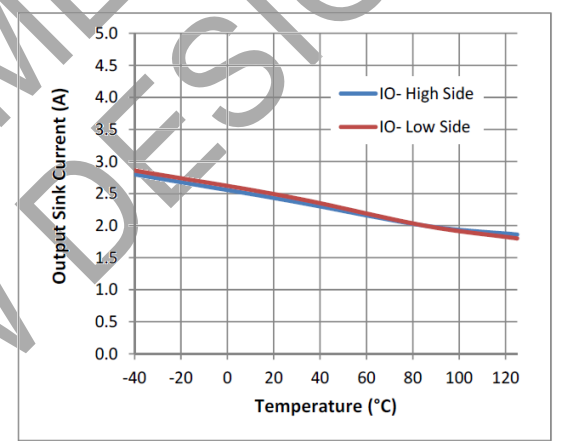
**Figure 17.** Output Source Current vs. Supply Voltage



**Figure 18.** Output Source Current vs. Temperature

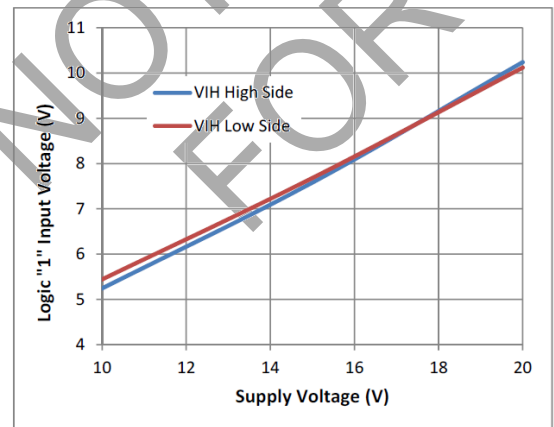


**Figure 19.** Output Sink Current vs. Supply Voltage

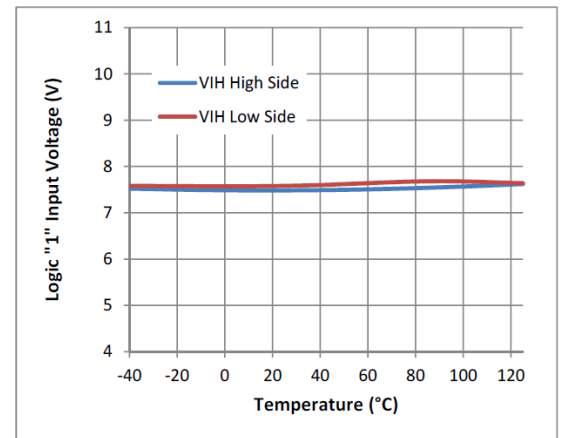


**Figure 20.** Output Sink Current vs. Temperature

Note: graphs overlap one another



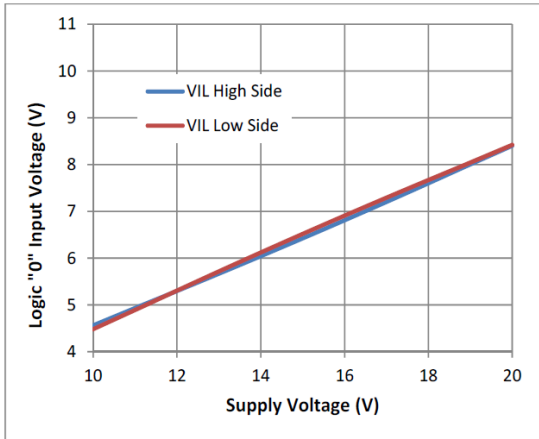
**Figure 21.** Logic 1 Input Voltage vs. Supply Voltage



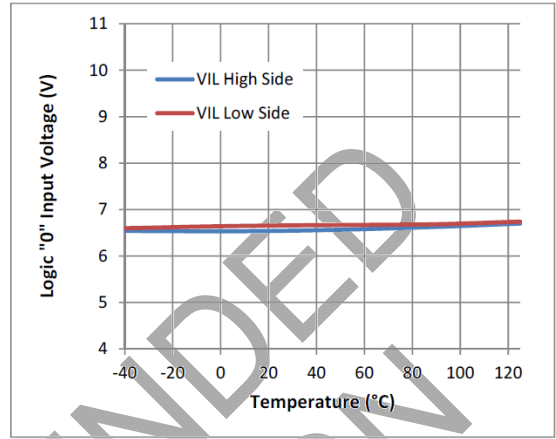
**Figure 22.** Logic 1 Input Voltage vs. Temperature



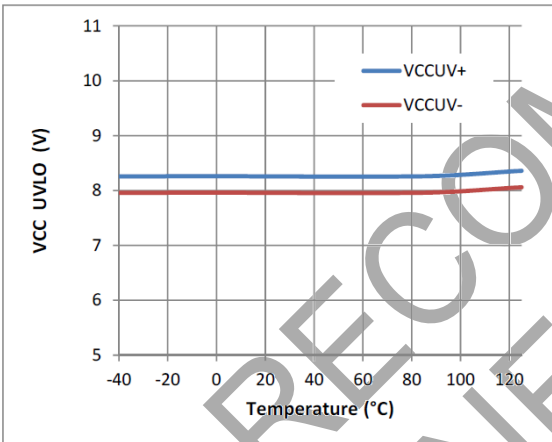
**Typical Performance Characteristics** ( $V_{CC} = 15V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.) (continued)



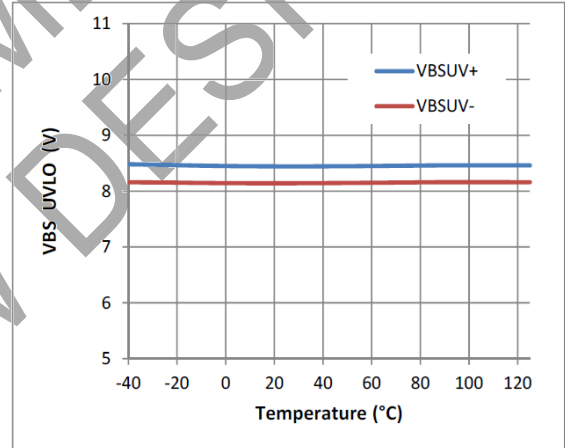
**Figure 23.** Logic 0 Input Voltage vs. Supply Voltage



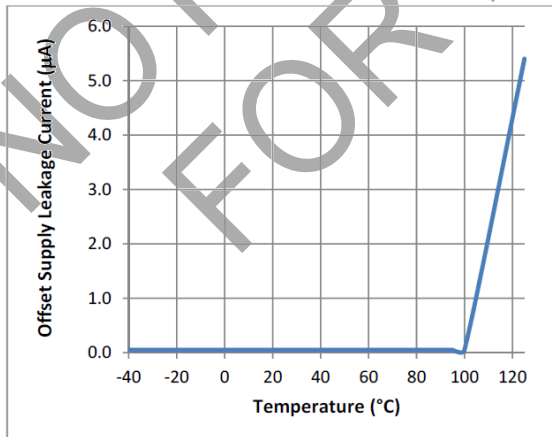
**Figure 24.** Logic 0 Input Voltage vs. Temperature



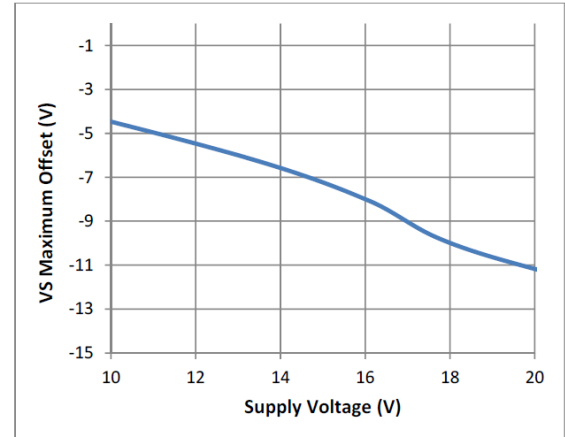
**Figure 25.**  $V_{CC}$  UVLO vs. Temperature



**Figure 26.**  $V_{BS}$  UVLO vs. Temperature

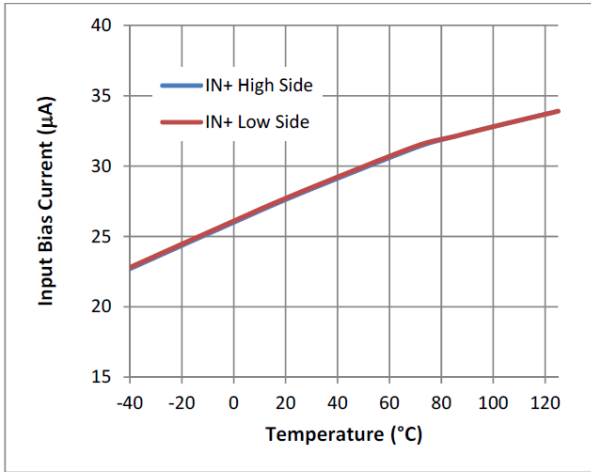


**Figure 27.** Offset Supply Leakage Current vs. Temperature

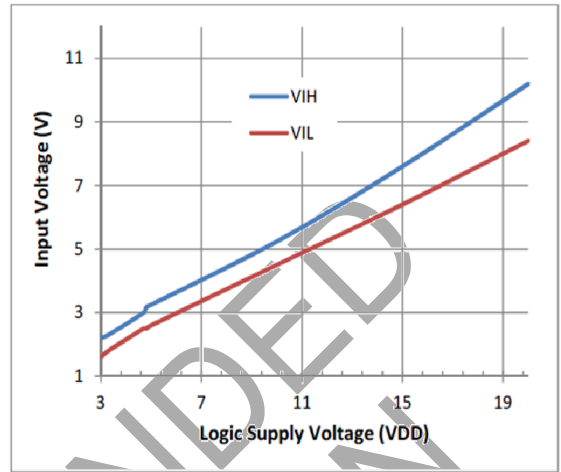


**Figure 28.**  $V_S$  Maximum Offset vs. Supply Voltage

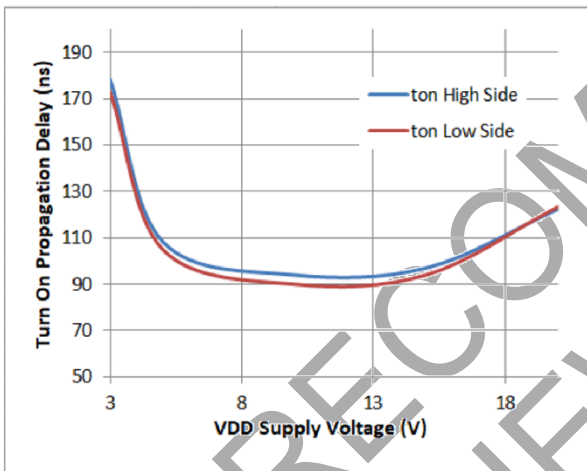
**Typical Performance Characteristics** ( $V_{CC} = 15V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.) (continued)



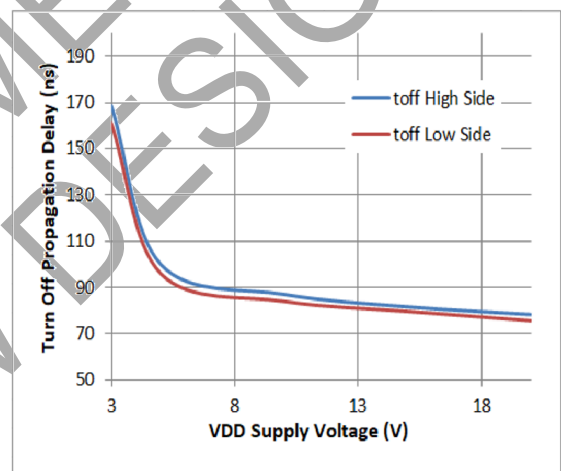
**Figure 29.** Input Bias Current vs. Temperature



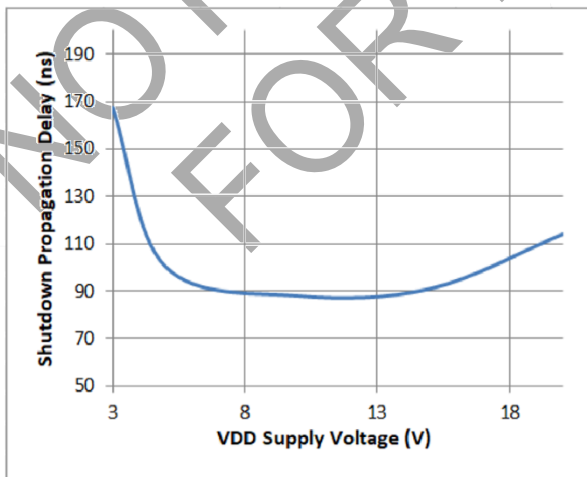
**Figure 30.** Input Voltage vs. Logic Supply Voltage



**Figure 31.** Turn-On Propagation Delay vs. Logic Supply Voltage



**Figure 32.** Turn-Off Propagation Delay vs. Logic Supply Voltage

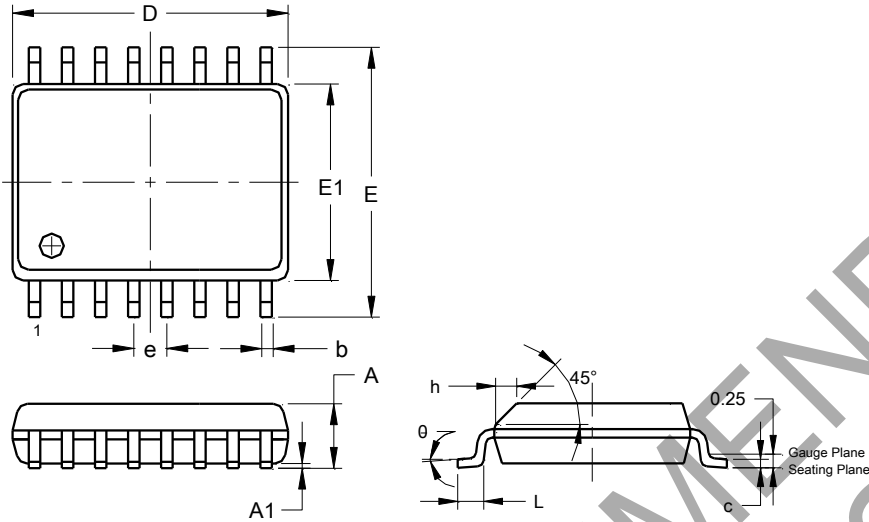


**Figure 33.** Shutdown Propagation Delay vs. Logic Supply Voltage

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-16 (Type TH)**

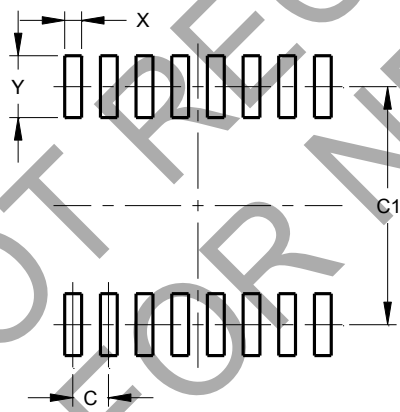


SO-16 (Type TH)			
Dim	Min	Max	Typ
A	2.36	2.64	--
A1	0.10	0.30	--
b	0.33	0.51	--
c	0.229	0.318	--
D	10.11	10.46	10.29
E	10.01	10.64	10.33
E1	7.42	7.59	7.52
e	--	--	1.27
h	--	--	0.48
L	0.41	1.27	--
θ	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-16 (Type TH)**



Dimensions	Value (in mm)
C	1.27
C1	8.46
X	0.60
Y	2.20

Note: 10. For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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